

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of the Claims:**

1. (Currently Amended) An apparatus, comprising:  
an absorber section of a heat pipe attached to a first end of a base of the heat pipe, the absorber section to remove heat from a heat spreader; and  
an ~~evaporator~~ dissipater section of a heat pipe attached to a ~~first~~ second  
end of a base of the heat pipe, wherein a width of the ~~evaporator~~ dissipater  
section is greater than a width of the base, and the ~~evaporator~~ dissipater section  
having a size of at least a surface area of a the heat spreader.
2. - 5. (Cancelled)
6. (Previously Amended) The apparatus of Claim 5, further comprising:  
a plurality of fins formed of the second end of the base, the plurality of  
fins attached to a bottom surface of the heat dissipater, the fins having a length  
approximately equal to the width of the base.

7. (Cancelled)

8. (Withdrawn) An apparatus, comprising:

a base formed of a heat conductive material, the base having a first end and a second end;

a heat absorber attached to the first end of the base, the heat absorber having a first width greater than a second width of the base, the heat absorber having a top surface and a planar bottom surface, the planar bottom surface having a first surface area approximately equal to a second surface area of an integrated heat spreader attached to a silicon die; and

a heat dissipator attached to the second end of the base.

9. (Withdrawn) The apparatus of Claim 8, wherein the heat dissipator has a third width approximately equal to the second width of the base.

10. (Withdrawn) The apparatus of Claim 8, further comprising:

a plurality of fins formed of the heat conductive material, the plurality of fins attached to a bottom surface of the heat dissipator, the plurality of fins having a length approximately equal to the second width of the base.

11. (Withdrawn) The apparatus of Claim 10, wherein the heat conductive material is a material selected from the group consisting of copper, a copper alloy, or aluminum.

12. (Withdrawn) The apparatus of Claim 8, wherein the heat conductive material is copper.

13. (Currently Amended) A computer system, comprising:  
a central processing unit (CPU); ~~and~~  
a heat absorber attached to a first end of a base of a heat pipe; and  
~~an evaporator section of a heat pipe~~ heat dissipater attached to a ~~first~~  
second end of a the base of the heat pipe, wherein a width of the ~~evaporator~~  
section heat dissipater is greater than a width of the base, and the ~~evaporator~~  
section heat dissipater having a size of at least a surface area of a heat spreader.

14-16. (Cancelled)

17. (Previously Amended) The computer system of Claim 16, further comprising:  
a plurality of fins formed on the second end of the base, the plurality of  
fins attached to a bottom surface of the heat dissipator, the plurality of fins

having a length approximately equal to the width of the base.

18. (Cancelled)